

ABSTRACT OF THE DISCLOSURE

BALL GRID ARRAY CONNECTOR

During the surface mounting of another electronic part on a surface of a circuit board reverse from that on which a connector has been mounted, soldered portions of the connector are also exposed to high temperature, and therefore soften. Because the center of gravity of the connector is biased away from the center of the soldering region, a rotational moment is generated, causing the solder balls close to an end portion of a base housing to be at risk of separating from the circuit board, making the connection therebetween unstable. However, due to the surface tension of melted solder at a fine portion of a solder peg, the end portion does not separate from the circuit board. Therefore, even when the rotational moment is generated, the connector does not change its position and an upper surface thereof remains parallel to the circuit board.

Figure 1



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